

**Amendments to the Claims:**

1. (Currently Amended) An implant comprising  
a sensor device being fixedly connected to a first end of a longitudinal carrier;  
an inductive coil connected to the sensor device via electrical connection lines  
that are arranged on the longitudinal carrier; and  
a covering encapsulating the sensor device, the carrier with the connection  
lines and the coil;  
wherein the carrier has a sufficient rigidity such that the sensor device is  
adapted to be guided by the carrier during implantation to a the target position and  
held in position at the target position, and that the covering part has means for  
providing a subcutaneous fastening, the carrier is flat with a rectangular cross-  
section.
2. (Previously Presented) The implant according to claim 1, wherein  
the carrier is arranged at an angle  $<180^\circ$  relative to the plane, in which the  
coil windings of the inductive coil are arranged.
3. (Previously Presented) The implant according to claim 1, wherein  
there are provided two connection lines between the coil and the sensor  
device.
4. (Previously Presented) The implant according to claim 1, wherein  
the carrier is flat .
5. (Previously Presented) The implant according to claim 1 , further comprising  
a stiffening foil being provided in the covering part.
6. (Previously Presented) The implant according to claim 5, wherein  
the carrier is formed as at least one of a rod and a foil.

7. (Canceled)
8. (Previously Presented) The implant according to claim 1, wherein a frame is fastened at the first end of the carrier , the sensor device positively fits within the frame.
9. (Previously Presented) The implant according to claim 8, wherein the frame is formed one piece with the carrier .
10. (Previously Presented) The implant according to claim 1, wherein the carrier is formed as a common carrier for the electrical connection lines and the coil windings.
11. (Previously Presented) The implant according to claim 1, wherein the sensor device comprises at least one pressure sensor.
12. (Previously Presented) The implant according to claim 1, wherein the covering part encapsulating the coil is adapted to be arranged in an interior of the brain.
13. (Previously Presented) The implant according to claim 12, wherein the encapsulating material of the covering part covering the sensor device is formed as a pressure transmitting medium.
14. (Previously Presented) The implant according to claim 1, wherein the sensor device is adapted to be positioned for at least one of an intraparenchymal and a intraventricular pressure measurement.
15. (Previously Presented) An implant according to claim 2, wherein the angle is from 60° to 120°.

Serial No. 10/579,265

16. (Previously Presented) An implant according to claim 12, wherein the covering part encapsulating the coil is adapted to be arranged in the epidural.

17. (Previously Presented) An implant according to claim 13, wherein the encapsulating material of the covering part covering the sensor device is made of silicon.